

METHODS AND APPARATUS FOR INTEGRATED CIRCUIT DEVICE
POWER DISTRIBUTION VIA INTERNAL WIRE BONDS

Abstract

5 An integrated circuit device comprising a die having a top surface with a peripheral region and an interior region surrounded by the peripheral region. Bond pads are disposed in the peripheral region of the die. One or more internal buses are disposed in the interior region of the die. The one or more internal buses distribute power to internal node points of the die. One or more bond wires connect one or more peripheral bond pads with one or more internal buses.